

12/01/98

ASSIGNMENT RECORDATION COVER SHEET
-PATENTS ONLY-

JC549 U.S. PTO
09/20/2020
12/01/98

To: Honorable Commissioner of Patents and Trademarks:

Please record the attached original document(s) or copy thereof.

Name of conveying party(ies)

a) Ming-Tsung Tung

2. Name and address of receiving party(ies):

a) Name: United Microelectronics Corp.
Address: No. 3, Li-Hsin Rd. II,
Science-Based Industrial Park
Hsinchu, Taiwan, R.O.C.

12-15-1998



100920077

3. Nature of conveyance



Assignment



Security Agreement



Other _____



Merger



Change of Name



License Agreement

Execution Date: November 10, 1998

4. Application Number(s) or Patent Number(s): Unassigned

The title of the (new) application is:

09203020

MANUFACTURING METHOD FOR REDUCING THE THICKNESS OF A DIELECTRIC LAYER

5. Please send all correspondence concerning this (these) documents to:

Paul L. Hickman
HICKMAN & MARTINE, LLP
P.O. Box 52037
Palo Alto, CA 94303-0746
Tel. No.: (650) 470-7430
Fax No.: (650) 470-7440

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$40.00



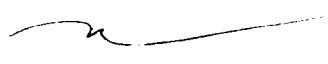
Enclosed



Authorized to be charged to Deposit Account No. 50-0384
(Order No. _____)

8. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Date: December 1, 1998


Brian R. Coleman
Registration No. 39,145

Attorney Docket No. JCIPP103

12/09/1998 DEBITER 00000048 09203020 40.00 DP
PATENT

REEL: 9631 FRAME: 0115

ASSIGNMENT

WHEREAS,

1. Ming-Tsung Tung

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **MANUFACTURING METHOD FOR REDUCING THE THICKNESS OF A DIELECTRIC LAYER**

[] Filed: Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, United Microelectronics Corp.

No. 3, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Ming-Tsung Tung ~~Dec~~ Nov. 10, 1998
Sole or First Joint Inventor: Ming-Tsung Tung